



MEG-00-012C

09/821,546

AF IFW

June 7, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/821,546 03/30/2001

J. Y. LEE

“A STRUCTURE AND MANUFACTURING
METHOD OF CHIP SCALE PACKAGE”

Grp. Art Unit: 2811

D. W. OWENS

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action mailed April 20, 2007, please amend the above-identified application for patent and consider the remarks as follows:

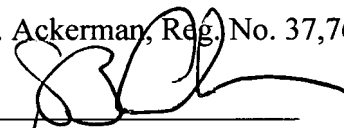
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jun. 20, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date


6/20/07

Amendments to the Specification begins on page 3 of this paper.

Amendments to the Claims are reflected in the listing of the Claims which begins on page 5 of this paper.

Remarks/Arguments begin on page 33 of this paper.